Texas Instruments

Bill of Materials

TI DESIGNS

TIDM-DELFINO-ETHERCAT

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint	Note
1	1			PWB,C2000-ET1100 ADAPTER BOARD				
2	1			LOGIC,C2000-ET1100 ADAPTER BOARD				
3	1	U5		IC,BGA128,.8mm,ETHERCAT SLAVE CONTROLLER	Beckhoff	ET1100	bga128-8mm	
4	2	U3, U6		IC,QFN32,SINGLE PORT 10/100Mbs ETHERNET PHY TRANSCEIVER,LOW POWER	Texas Instruments	TLK105LRHBR	QFN32_202SQ	
5	1	U7		IC,QSOP16,LOW VOLTAGE,QUAD 2:1 MULTIPLEXER/DEMULTIPLEXER	Texas Instruments	SN74CBTLV3257PWR	tssop16-14x70	
6	1	U2		IC,QSOP20,LOW VOLTAGE,QUICK SWITCH	Texas Instruments	SN74CBTLV3245ADBQR	dbq20-14x70	
7	1	U1		IC,SO5,SINGLE BUFFER/DRIVER	Texas Instruments	SN74LVC1G07DCKR	dck-5	
8	1	U4	16k	IC,SO8,SERIAL EEPROM,16K-BIT	Catalyst Semiconductor, In	CAT24C16WI-GT3	so8-25x75-295	
9	1	U8	3.3v,1.6A	IC,SON8,STEP-DOWN DC-DC	Texas Instruments	TPS62063DSGT	dsg8-11x20	
10	1	Y1	25MHz	CRYSTAL,SMT,4 PIN,25MHz	ECS	ECS-250-20-33-TR	xtal4-47x51-ecx32	
11	2	DS1, DS2	Green	LED,SMT 1206,GREEN	LITEON	LTST-C150GKT	led1206-59x59	
12	1	L2	1uH	INDUCTOR,SMT,1uH	Murata Electronics	LQH44PN1R0NP0L	ind-LQH44p	
13	1	L1	220ohm	FERRITE BEAD,SMT 0603,220 OHM	Murata Electronics	BLM18AG221SN1D	l603-35x45	
14	2	C41, C83	4700pF	CAP,CER,SMT 1206,4700pF,200V,+10/-10%,X7R	AVX Corporation	12062C472KAT2A	C1206-40X70	
15	2	C4, C6	22uF	CAP,CER,SMT 1206,22uF,10V	Taiyo Yuden	LMK316F226ZL-T	C1206-40X70	
16	8	C12, C14, C15, C33, C55, C58, C77,	1uF	CAP,CER,SMT 0603,1uF,6.3V,X5R,+/-10%	Murata Electronics	GRM188R60J105KA01D	c603-35x45	
17	8	C22, C26, C34, C38, C44, C74, C78,	10uF	CAP,CER,SMT 0603,10uF,6.3V,X5R,+/-20%	Murata Electronics	GRM188R60J106ME47D	c603-35x45	
18	15	C2, C27, C28, C30, C31, C43, C46,	220pF	CAP,CER,SMT 0402,220pF,50V,NPO	Panasonic	ECJ-0EC1H221J	c402-25	
19	2	C3, C7	15pF	CAP,CER,SMT 0402,15pF,50V,NPO	Yageo	CC0402JRNPO9BN150	c402-25	
20	2	C1, C37	100pF	CAP,CER,SMT 0402,100pF,50V,+/-5%,NPO	Kemet Electronics Corpora	C0402C101J5GAC	c402-25	
21	5	C8, C25, C32, C73, C76	1000pF	CAP,CER,SMT 0402,1000pF,50V,+/-5%,NPO	TDK Corporation	CGJ2B2C0G1H102J	c402-25	
22	35	C5, C9, C10, C11, C13, C16, C17,	0.1uF,16V	CAP,CER,SMT 0402,.1uF,16V,+/-	Murata Electronics	GCM155R71C104KA55	c402-25	
23	4	C18, C24, C61, C72	0.01uF	CAP,CER,SMT 0402,.01uF,16V,+/-10%,X7R	Kemet Electronics Corpora	C0402C103K4RAC	c402-25	
24	18	R15, R16, R17, R22, R30, R32, R36,	2.2kohm	RES,SMT 0201,2.2K OHM,5%,1/20 WATT	Yageo	RC0201JR-072K2L	r201-6p6spc	
25	2	RJ1, RJ2	0 ohm	RES,SMT 0402,0 OHM,1/16 WATT	Yageo	RC0402JR-070RL	r402-25	
26	2	R1, R8	10kohm	RES,SMT 0402,10K,1%,1/16 WATT	Yageo	RC0402FR-0710KL	r402-25	
27	1	R19	11kohm	RES,SMT 0402,11K OHM,1%,1/16 WATT	Panasonic	ERJ-2RKF1102X	r402-25	
28	20	R13, R18, R20, R24, R25, R26, R27,	4.7kohm	RES,SMT 0402,4.7K,1%,1/16 WATT	Vishay Intertechnology	CRCW04024K70FKED	r402-25	
29	2	R40, R65	4.87kohm	RES,SMT 0402,4.87K,1%,1/16 WATT	Panasonic	ERJ-2RKF4871X	r402-25	

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30	14	R2, R3, R4, R5, R6, R7, R9, R10, R11, R12, R39, R58, R70, R71	49.9ohm	RES,SMT 0402,49.9 OHM,1%,1/16 WATT	Panasonic	ERJ-2RKF49R9X	r402-25	
31	6	R14, R43, R51, R72, R74, R75	470ohm	RES,SMT 0603,470 OHM,5%,1/16 WATT	Panasonic	ERJ-3GEYJ471V	r603-35X45	
32	1	SW1		SWITCH,DIP,SMT,HALF-PITCH,2 POS.	C&K/Unimax, Inc.	TDA02H0SB1R	sw2-30x50-tda	
33	1	J6		CONN,SMT,RECEPTACLE,60 POS.,.4mm SPC.,4mm STACKING HEIGHT	Hirose Electric, Inc.	DF40HC-(4.0)60DS-0.4V	df40c_60ds	
34	2	P1, P0		CONN,JACK,RJ45,INTEGRATED MAGNETICS AND LED'S,8 CONTACTS,SHIELDED	Pulse Engineering	J1011F01PNL	RJ45-PULSE_J1-SHLD	
35	2	J3, J10		HEADER,3 X 1,VERTICAL,2mm	Harwin	M22-2510305	hdr1x3-6040-2mm	
36	1	TP15		TEST POINT,SMT,MINIATURE	Keystone Electronics Corp.	5015	TP1-70X135	
37	10	TP2, TP3, TP4, TP5, TP6, TP7, TP9, TP11, TP13, TP14		(NO-POP) TEST POINT,SMT,.03" DIA.			tp30	
38	10	R23, R29, R31, R35, R38, R53, R55, R56, R61, R64					r201-6p6spc	
39	2	R21, R60					r402-25	
40	5	TP1, TP8, TP10, TP12, TP16						
41	1	J9		CONN,HEADER,SHROUDED,2 POS	JST Corporation	B2B-EH-A(LF)(SN	conn2-eh	

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